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ULN2803A DARLINGTON TRANSISTOR ARRAY

DW OR N PACKAGE

(TOP VIEW)

1B Г

2B 🛛 2

3B 🛛 3

4B 🛛 4

5B 🛛 5

6B 6

7B 🛙 7

9

8B 🛛 8

GND

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18 11 1C

17 2C

16 3C

15 4C

14 5C

13 6C

12 7C

11 8C

10 COM

- 500-mA Rated Collector Current (Single Output)
- High-Voltage Outputs . . . 50 V
- Output Clamp Diodes
- Inputs Compatible With Various Types of Logic
- Relay Driver Applications
- Compatible with ULN2800A Series

description/ordering information

The ULN2803A is a high-voltage, high-current Darlington transistor array. The device consists of eight npn Darlington pairs that feature high-voltage outputs with common-cathode clamp diodes for switching inductive loads. The collector-current rating of each Darlington pair is 500 mA. The Darlington pairs may be connected in parallel for higher current capability.

Applications include relay drivers, hammer drivers, lamp drivers, display drivers (LED and gas discharge), line drivers, and logic buffers. The ULN2803A has a 2.7-k Ω series base resistor for each Darlington pair for operation directly with TTL or 5-V CMOS devices.

ORDERING INFORMATION

/	ТА	PACKAGET		ORDERABLE PART NUMBER	TOP-SIDE MARKING	
		PDIP (N)	Tube of 20	ULN2803AN	ULN2803AN	
	–40°C to 85°C		Tube of 40	ULN2803ADW	ULN2803A	
		SOIC (DW)	Reel of 2000	ULN2003ADWR	ULIN2803A	

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.





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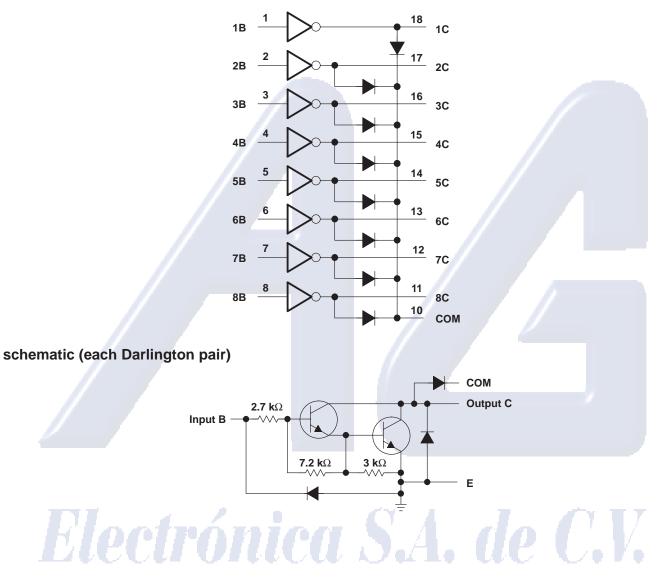
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logic diagram





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absolute maximum ratings at 25°C free-air temperature (unless otherwise noted)[†]

Collector-emitter voltage	50 V
Input voltage (see Note 1)	
Continuous collector current	0 mA
Output clamp diode current	0 mA
Total substrate-terminal current	-2.5 A
Package thermal impedance, θ _{JA} (see Notes 2 and 3): DW package	°C/W
N package TBD	°C/W
Operating virtual junction temperature, T _J	150°C
Storage temperature range, T _{stg} –65°C to 2	50°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values, unless otherwise noted, are with respect to the emitter/substrate terminal GND.

- 2. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.

electrical characteristics at 25°C free-air temperature (unless otherwise noted)

	PARAMETER	TEST CO	NDITIONS	MIN	TYP	MAX	UNIT
ICEX	Collector cutoff current	V _{CE} = 50 V, See Figure 1	lı = 0,			50	μΑ
II(off)	Off-state input current	$V_{CE} = 50 \text{ V},$ $T_{A} = 70^{\circ}\text{C},$	$I_{C} = 500 \ \mu A$, See Figure 2	50	65		μΑ
I _{I(on)}	Input current	V _I = 3.85 V,	See Figure 3		0.93	1.35	mA
			I _C = 200 mA		1	2.4	
V _{I(on)}	On-state input voltage	V _{CE} = 2 V, See Figure 4	I _C = 250 mA			2.7	V
		Coo rigaro r	I _C = 300 mA			3	
		I _I = 250 μA, See Figure 5	I _C = 100 mA,		0.9	1.1	
V _{CE(sat)}	Collector-emitter saturation voltage	I _I = 350 μA, See Figure 5	I _C = 200 mA,		1	1.3	V
	ootrónioa	I _I = 500 μA, See Figure 5	I _C = 350 mA,		1.3	1.6	
I _R	Clamp diode reverse current	V _R = 50 V,	See Figure 6		2.0	50	μΑ
VF	Clamp diode forward voltage	I _F = 350 mA,	See Figure 7		1.7	2	V
Ci	Input capacitance	$V_{I} = 0 V,$	f = 1 MHz		15	25	pF

switching characteristics at 25°C free-air temperature

	PARAMETER	TEST CO	NDITIONS	MIN	TYP	MAX	UNIT
^t PLH	Propagation delay time, low- to high-level output	V _S = 50 V,	R _L = 163 Ω,		130		
^t PHL	Propagation delay time, high- to low-level output	C _L = 15 pF,	See Figure 8		20		ns
V _{OH}	High-level output voltage after switching	V _S = 50 V, See Figure 9	$I_{O} \approx 300 \text{ mA},$	V _S - 20			mV



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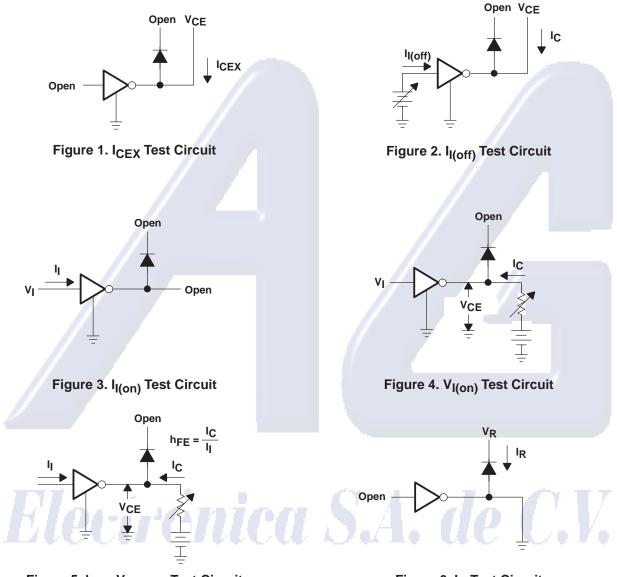




Figure 6. I_R Test Circuit

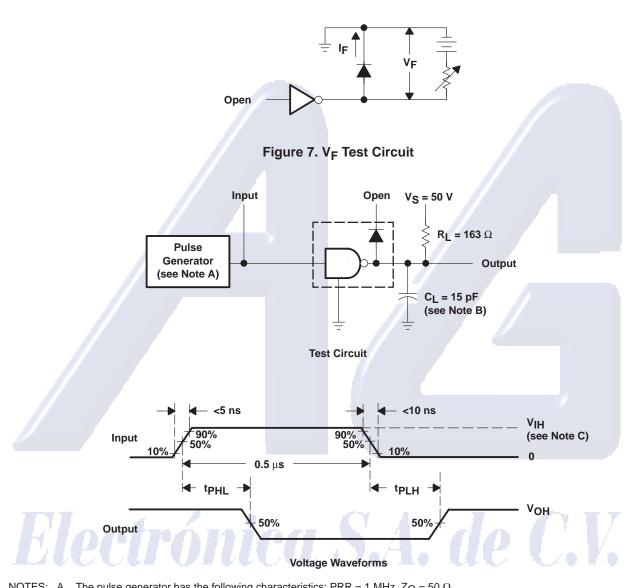


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PARAMETER MEASUREMENT INFORMATION

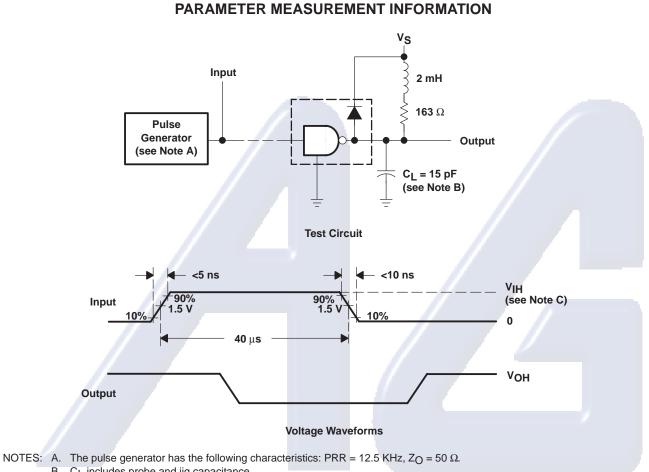
NOTES: A. The pulse generator has the following characteristics: PRR = 1 MHz, Z_0 = 50 Ω .

B. CL includes probe and jig capacitance. C. $V_{IH} = 3 V$

Figure 8. Propagation Delay Times



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- B. CL includes probe and jig capacitance.
- C. $V_{IH} = 3 V$

Figure 9. Latch-Up Test

Electrónica S.A. de C.V.

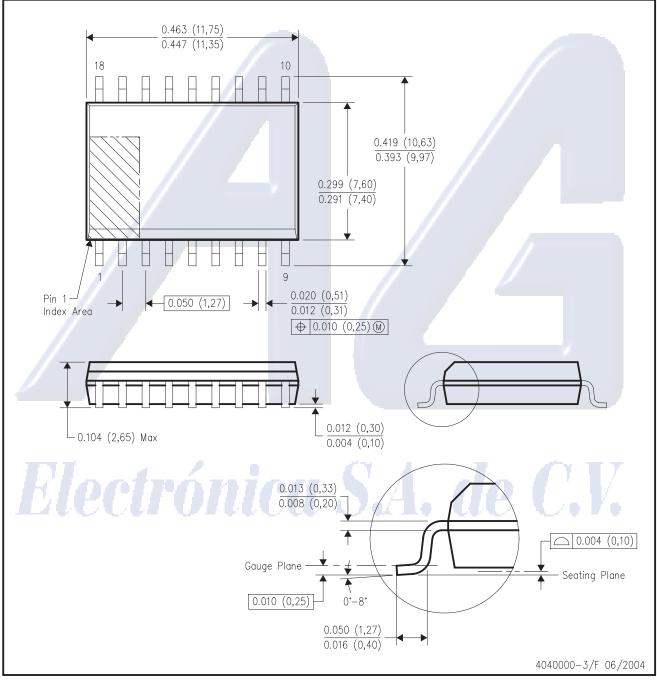


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PLASTIC SMALL-OUTLINE PACKAGE

DW (R-PDSO-G18)



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013 variation AB.



TEXAS FRUMENTS

PACKAGE OPTION ADDENDUM

4-Mar-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins F	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	n MSL Peak Temp ⁽³⁾
ULN2803ADW	ACTIVE	SOIC	DW	18	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
ULN2803ADWR	ACTIVE	SOIC	DW	18	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
ULN2803AN	ACTIVE	PDIP	Ν	18	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

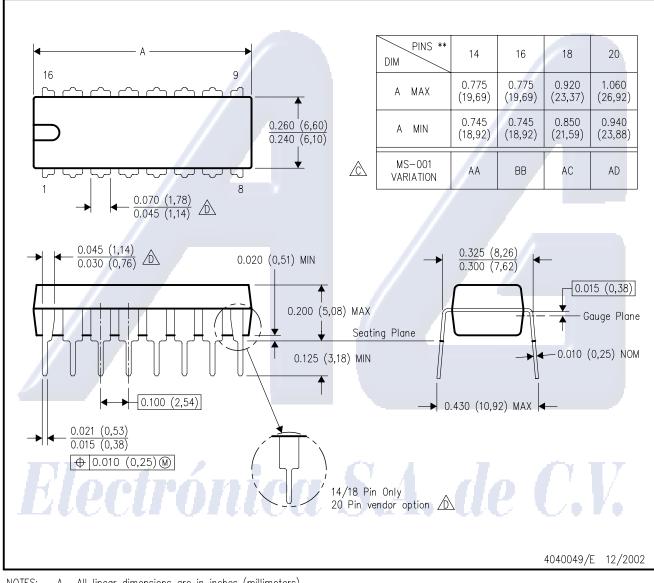
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MECHANICAL DATA

N (R-PDIP-T**) 16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters). B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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